



(非累積公差)
推奨基板取付け穴寸法 (コネクタ搭載面)
RECOMEND PC BOARD HOLE PATTERN (NOT ACCUMULATE TOLERANCE)
PC BOARD THICKNESSES: 1.6 ± 0.1 (PC 基板厚: 1.6 ± 0.1)

- 注記
- ① 材料: ハウジング: ガラス入りポリエステル樹脂
CONTACT: 銅合金 熱可塑性ポリエステル樹脂
RETENTION LEG: 銅合金
 - ② めっき: (コンタクト接触部) ニッケル下地の上に 0.38 μMIN 金メッキ
 - ③ めっき: (コンタクト接触部) ニッケル下地の上に 0.76 μMIN 金メッキ
 - ④ めっき: (コンタクト全面) ニッケル下地の上に 2.0 μMIN スズメッキ
 - ⑤ (リテンションレグとコンタクト半田付け部) ニッケル下地の上に半田メッキ
 - ⑥ めっき: リテンションレグとコンタクト半田付け部
: ニッケル下地の上にスズめっき
- NOTES
- ① MATERIAL HOUSING: GLASS FILED POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
 - ② FINISH (CONTACT AREA): 0.38 μMIN GOLD PLATED OVER NICKEL
 - ③ FINISH (CONTACT AREA): 0.76 μMIN GOLD PLATED OVER NICKEL
 - ④ FINISH (CONTACT): 2.0 μMIN TIN PLATED OVER NICKEL
 - ⑤ FINISH (RETENTION LEG AND CONTACT TAIL): TIN-LEAD
- PLATED OVER NICKEL
 - ⑥ FINISH (RETENTION LEG): TIN PLATED
(CONTACT TAIL) OVER NICKEL

NUMBER 178137

METRIC

3rd ANGLE PROJECTION

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST

XY	△6 △4	3-178137-5	
	△6 △3	3-178137-3	
YY	△6 △4	2-178137-5	
	△6 △3	2-178137-3	
XX	△6 △2	2-178137-2	
	△6 △4	1-178137-5	
	△6 △3	1-178137-3	
	△6 △2	1-178137-2	
KEYING LOCATION	KEYING NAME	FINISH	PART NO.

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WIRE RANGE		INSULATION DIA		NAME			
mm ² (AWG -)		mmφ		DYNAMIC D-3100 3.81 X 7.62 PITCH(H) 6POS. HDR CONN. ASS'Y (KEY;XX,YY,XY)			
C	REVISED (FJD0-0039-03)	TS	S.M.	MATERIAL		FINISH	
B	REVISED (FJD0-0114-03)	TS	S.M.	SEE NOTE		SEE NOTE	
A1	REVISED (FJ00-2444-95)	NM	S.M.	注記参照		注記参照	
A	REDRAWN (ECN J-1432)	Y.T	S.M.	DR. Y.TANAKA		DE. Y.TANAKA	
LTR	REVISION RECORD	DR	CHK	CHK. S.MANABE		APP. S.MANABE	
				DR. 1-JULY-'92		DE. 1-JULY-'92	
				6-JUL-'92		6-JUL-'92	
GENERAL TOLERANCE		SIZE	LOC	NUMBER			
10% 30% 50%		A3	J	C-178137			
SCALE		REV.		SHEET			
2-1		C		1 OF 1			